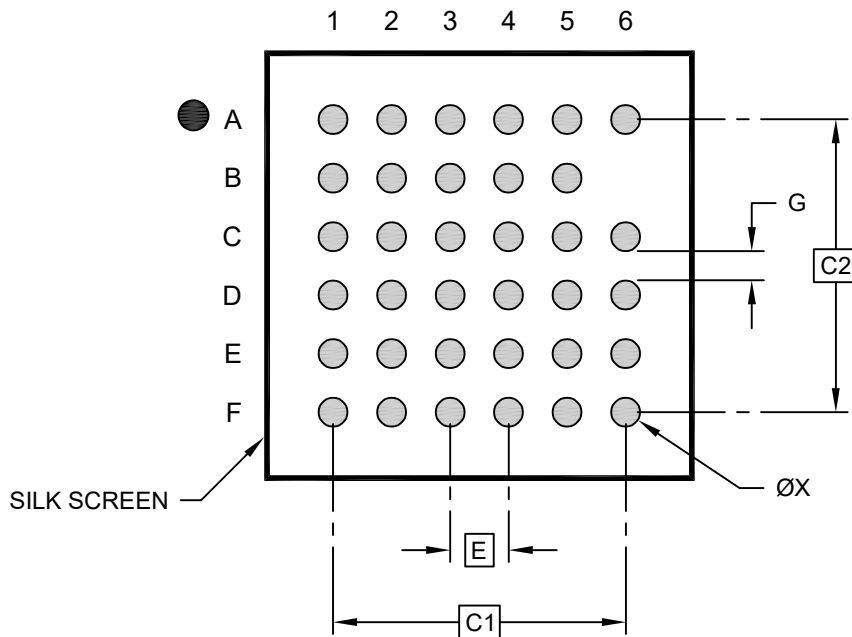


# 35-Ball Wafer Level Chip Scale Package (GFB) - 2.78x2.578x0.443 mm Body [WCLSP] Atmel Global Package Code GJS

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



## RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Contact Pad Spacing	C1	2.00 BSC		
Contact Pad Spacing	C2	2.00 BSC		
Contact Pad Width	X			0.20
Contact Pad to Contact Pad (X35)	G	0.20		

### Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.